

IN THE CLAIMS:

Both of the claims that remain pending and under consideration in the above-referenced application are reproduced below.

Please enter the claims as follows:

1. (Twice amended) A multiple-die, low-profile semiconductor device comprising:
- [ a. ]a lead-frame paddle supported by a lead frame;
  - [ b. ]a controlled, first[,] thin[-] adhesive layer of about 0.001 inches to about 0.005 inches affixing a first die above the paddle;
  - [ c. ]a plurality of thin wires having [a] first low-loop wire [bond] bonds to a plurality of first [diebonding] die-bonding pads, said first low-loop wire [bond] bonds having [a] wire [height] heights above the [bonding pad] first die-bonding pads of at most about 0.006 inches, and [a second] other wire [bond] bonds to a plurality of adjacent lead-frame lead fingers;
  - [ d. ]a second thin[-] adhesive layer of about 0.008 inches to about 0.010 inches affixing a second die above the first die;
  - [ e. ]a second plurality of thin wires having second low-loop wire bonds to a plurality of second die-bonding pads and [second] other wire bonds to the plurality of lead fingers;
  - [ f. ]two additional dies affixed above the second die by additional subsequent layers of adhesive of about 0.008 inches to about 0.010 inches and having additional thin wires bonded to additional bonding pads and lead fingers; and
  - [ g. ]an [encapsulated] encapsulation layer surrounding all dies, adhesive layers, and thin wires wherein a total encapsulated-package height is at most about 0.110 inches.

2. (Twice amended) A multiple-die, low-profile semiconductor device comprising:
- [ a. ]a lead-frame paddle supported by a lead frame;
  - [ b. ]a controlled, first[,] thin[-] adhesive layer of about 0.001 to about 0.005 inches

affixing a first die above the paddle;

- c. ]a plurality of thin wires having [a] first low-loop wire [bond] bonds to a plurality of first die-bonding pads, said first low-loop wire [ball bond] bonds having [a] wire [height] heights above the first die-bonding pads of at most about 0.006 inches, and [a second] other wire [bond] bonds to a plurality of adjacent lead-frame lead fingers;
- d. ]a second thin[-] adhesive layer of about 0.008 to about 0.010 inches affixing a second die above the first die;
- e. ]a second plurality of thin wires having second low-loop wire bonds to a plurality of second die-bonding pads and [second] other wire bonds to the plurality of lead fingers;
- f. ]an [encapsulated] encapsulation layer surrounding all die adhesive layers and thin wires wherein a total encapsulation[-] layer height above an uppermost die of the multiple-die, low-profile stack is about [0.070] 0.010 inches to about 0.012 inches.
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